AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Previously Presented) A method of manufacturing a wafer assembly comprising:
   a chip wafer onto which a cover wafer is deposited, the chip wafer comprising an active face and an inactive face, the active face comprising chip elements, the cover wafer being provided with a chip-element-receiving cavity located above a chip element, the method comprising the following steps:
      a cover-wafer-depositing step, in which a cover wafer is deposited on the active face so as to obtain a wafer assembly, the cover wafer being provided with plurality of chip-receiving cavities, a chip-receiving cavity being located above a chip element, the cover wafer being made of an organic material; and
      a wafer assembly thinning step, in which the inactive face of the chip wafer is thinned.

2. (Original) The method according to claim 1, wherein the method further comprises a chip-fixing step, in which a chip is fixed in a chip-receiving cavity.

3. (Original) The method according to claim 1, wherein the cover-wafer is made of a photosensitive material.

4. (Original) The method according to claim 3, wherein the photosensitive material comprises Benzocyclo Butène.

5. (Original) The method according to claim 3, wherein the photosensitive material comprises a polyimide.

6. (Original) The method according to claim 3, wherein the photosensitive material comprises an epoxy-based material.

7. (Original) The method according to claim 2, wherein the method further comprises a wafer-assembly-cutting step, in which the wafer assembly is cut so as to obtain a plurality of chip assembly, a chip assembly comprising a chip element onto which a chip is fixed.

8. (Previously Presented) The method according to claim 2, wherein the chip elements are GSM chips.

9. (Previously Presented) The method according to claim 2, wherein the chips are RF chips.

10. (Previously Presented) The method according to claim 2, wherein the chips are DPA chips.

11. (Previously Presented) Method of manufacturing a portable device comprising:
a support layer provided with a cavity, the method comprising a chip-assembly-fixing step, in which a chip-assembly comprising a chip element onto which a chip is fixed in the cavity.

12. (Previously Presented) A chip assembly comprising a chip element onto which a chip is fixed.

13. (New) A chip assembly comprising:
a cover wafer disposed on a chip wafer; and
a cavity disposed on the cover wafer, wherein a chip element is fixed in the cavity.

14. (New) The chip assembly in accordance with claim 13, wherein the chip element is a Global System (GSM) for Mobile Communications chip.

15. (New) The chip assembly in accordance with claim 13, wherein the chip element is a Radio Frequency (RF) chip.

16. (New) The chip assembly in accordance with claim 13, wherein the chip element is a DPA chip.

17. (New) The chip assembly in accordance with claim 1, wherein the chip assembly is configured to be used in a smart card.

18. (New) The chip assembly in accordance with claim 11, wherein the chip assembly is configured to be used in a smart card.

19. (New) The chip assembly in accordance with claim 13, wherein the chip assembly is configured to be used in a smart card.